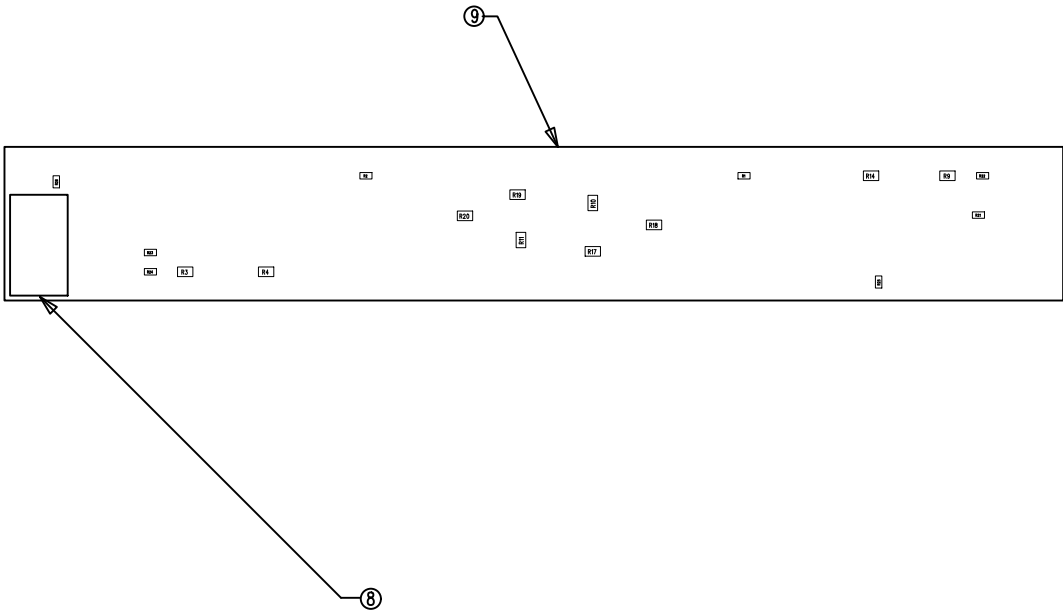



REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
	3	Production	E Benedict	9 AUG 19

NOTES: UNLESS OTHERWISE SPECIFIED

- WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
- MAXIMUM SOLDER TEMPERATURE IS 250 DEG C.
- ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP AND BOTTOM SIDE SMD.
- PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS.
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
- INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
- DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE
BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
- DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD
- APPLY DEMO S/N LABEL IN THIS AREA
- BREAK BOARDS AS A SET. DO NOT BREAK AT THIS LOCATION



APPROVALS		<div>  ANALOG DEVICES </div> <div> 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.analog.com ADI CONFIDENTIAL- FOR CUSTOMER USE ONLY </div>		
PCB DES.	EB			
APP ENG.	EB	TITLE: BOTTOM ASSEMBLY DRAWING DEMO CIRCUIT PMOD SPI EXTENDER		
		SIZE	IC NO. LTC4332	REV.
		N/A	DEMO CIRCUIT DC2799A	3
SCALE = NONE		SHT 2 OF 2		